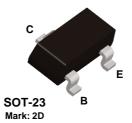


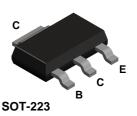
# MPSA92

# MMBTA92

# PZTA92







# **PNP High Voltage Amplifier**

This device is designed for high voltage driver applications. Sourced from Process 76.

## **Absolute Maximum Ratings\***

Symbol	Parameter	Value	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	300	V
V <sub>CBO</sub>	Collector-Base Voltage	300	V
V <sub>EBO</sub>	Emitter-Base Voltage	5.0	V
Ic	Collector Current - Continuous	500	mA
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- NOTES:

  1) These ratings are based on a maximum junction temperature of 150 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

#### **Thermal Characteristics**

TA = 25°C unless otherwise noted

Symbol	Characteristic	Max			Units
		MPSA92	*MMBTA92	**PZTA92	
P <sub>D</sub>	Total Device Dissipation	625	350	1,000	mW
	Derate above 25°C	5.0	2.8	8.0	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	83.3			°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	200	357	125	°C/W

<sup>\*</sup>Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06."

<sup>\*\*</sup>Device mounted on FR-4 PCB 36 mm X 18 mm X 1.5 mm; mounting pad for the collector lead min. 6 cm<sup>2</sup>.

## **PNP High Voltage Amplifier**

(continued)

. . . .

#### **Electrical Characteristics**

TA = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Max	Units
OFF CHA	RACTERISTICS				
$V_{(BR)CEO}$	Collector-Emitter Breakdown Voltage*	$I_C = 1.0 \text{ mA}, I_B = 0$	300		V
V <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage	$I_C = 100  \mu A,  I_E = 0$	300		V
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = 100  \mu A,  I_C = 0$	5.0		V
I <sub>CBO</sub>	Collector-Cutoff Current	$V_{CB} = 200 \text{ V}, I_{E} = 0$		0.25	μΑ
I <sub>EBO</sub>	Emitter-Cutoff Current	$V_{EB} = 3.0 \text{ V}, I_{C} = 0$		0.1	μΑ

#### ON CHARACTERISTICS\*

h <sub>FE</sub>	DC Current Gain	$I_C = 1.0 \text{ mA}, V_{CE} = 10 \text{ V}$	25		
		$I_C = 10 \text{ mA}, V_{CE} = 10 \text{ V}$	40		
		$I_C = 30 \text{ mA}, V_{CE} = 10 \text{ V}$	25		
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 20 \text{ mA}, I_B = 2.0 \text{ mA}$	5000	0.5	V
V <sub>BE(sat)</sub>	Base-Emitter Saturation Voltage	$I_C = 20 \text{ mA}, I_B = 2.0 \text{ mA}$	140	0.9	V

#### SMALL SIGNAL CHARACTERISTICS

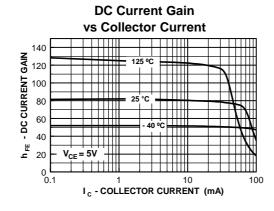
f <sub>T</sub>	Current Gain - Bandwidth Product	$I_C = 10 \text{ mA}, V_{CE} = 20 \text{ V},$ f = 100  MHz	50		MHz
C <sub>cb</sub>	Collector-Base Capacitance	$V_{CB} = 20 \text{ V}, I_{E} = 0, f = 1.0 \text{ MHz}$		6.0	pF

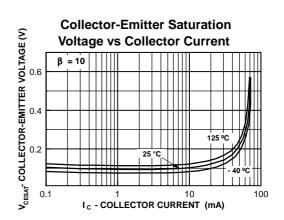
<sup>\*</sup>Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%

## Spice Model

PNP (Is=218.9f Xti=3 Eg=1.11 Vaf=100 Bf=99 Ne=1.307 Ise=218.9f Ikf=.2016 Xtb=1.5 Br=24.67 Nc=2 Isc=0 Ikr=0 Rc=7 Cjc=19.88p Mjc=.4876 Vjc=.75 Fc=.5 Cje=81.49p Mje=.3493 Vje=.75 Tr=516.9p Tf=1.395n Itf=1.5 Vtf=22 Xtf=270 Rb=10)

# **Typical Characteristics**

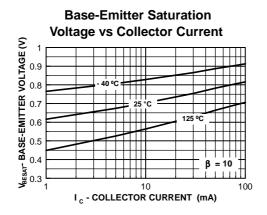


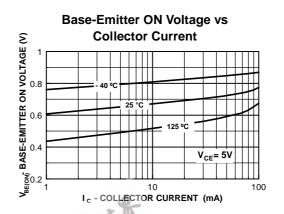


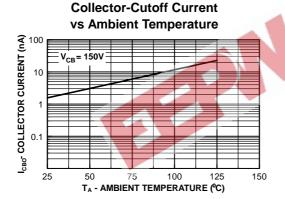
## **PNP High Voltage Amplifier**

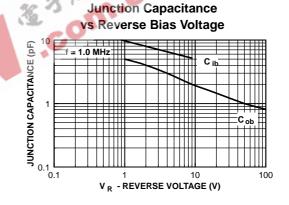
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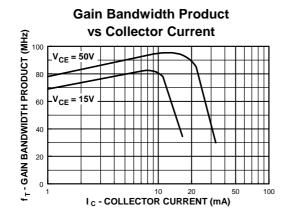
## Typical Characteristics (continued)

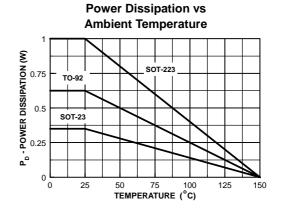


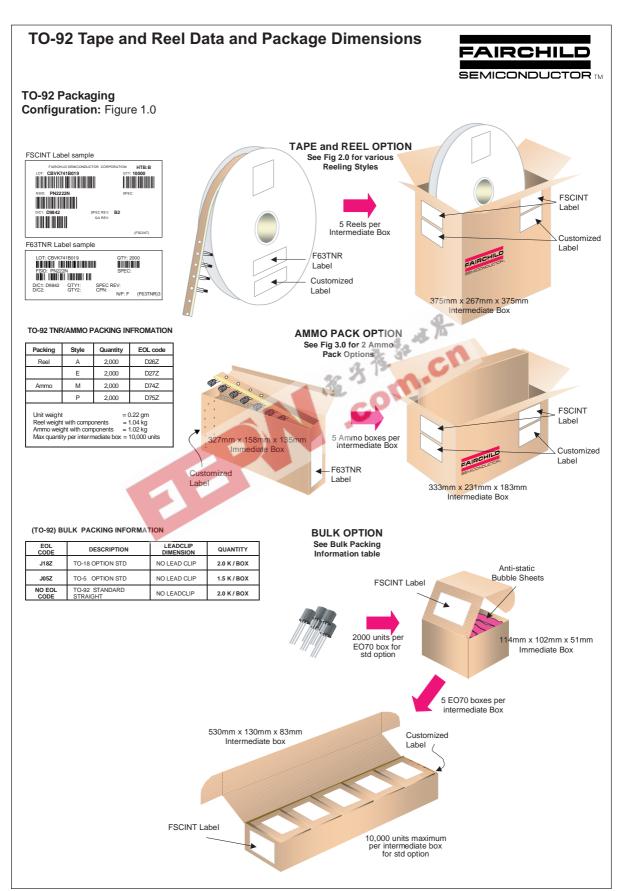








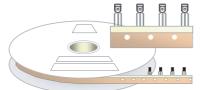




# TO-92 Tape and Reel Data and Package Dimensions, continued

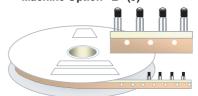
**TO-92 Reeling Style** Configuration: Figure 2.0

#### Machine Option "A" (H)



Style "A", D26Z, D70Z (s/h)

#### Machine Option "E" (J)



Style "E", D27Z, D71Z (s/h)

# **TO-92 Radial Ammo Packaging**

Configuration: Figure 3.0

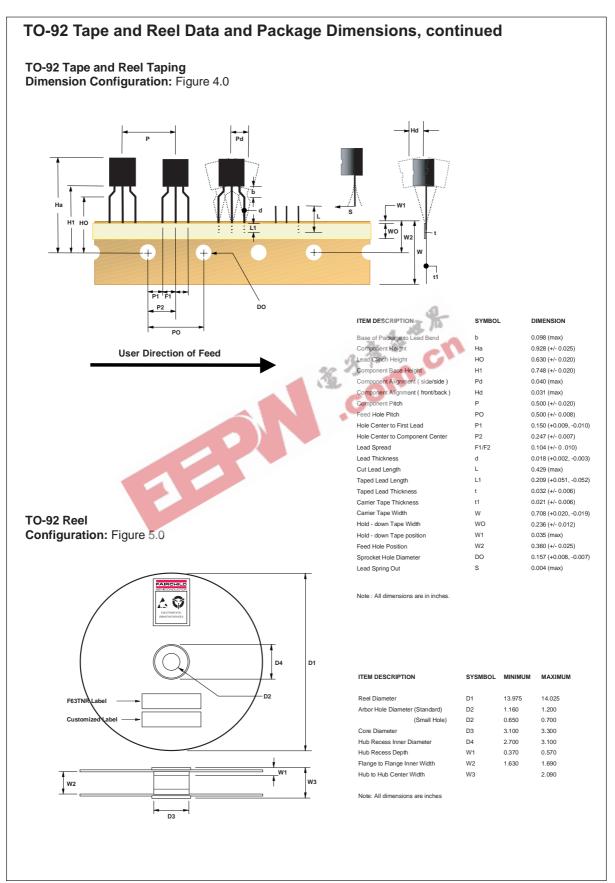


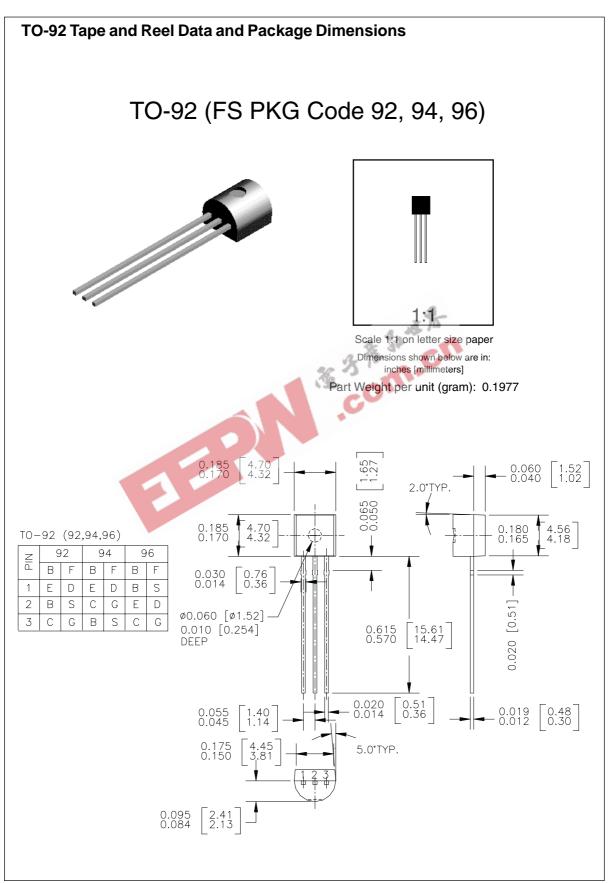
FIRST WIRE OFF IS EMITTER (ON PKG. 92) ADHESIVE TAPE IS ON BOTTOM SIDE FLAT OF TRANSISTOR IS ON BOTTOM

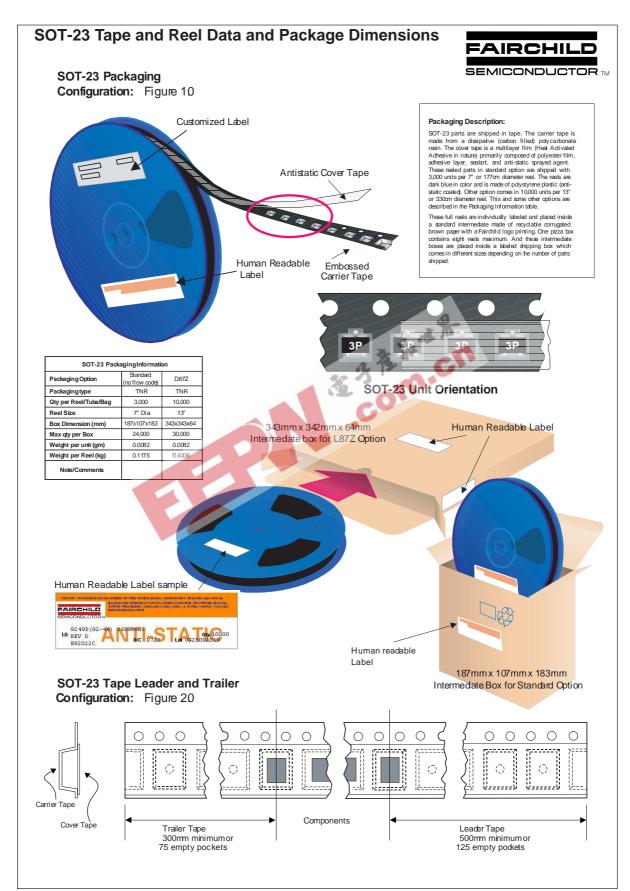
FIRST WIRE OFF IS EMITTER ADHESIVE TAPE IS ON THE TOP SIDE FLAT OF TRANSISTOR IS ON BOTTOM

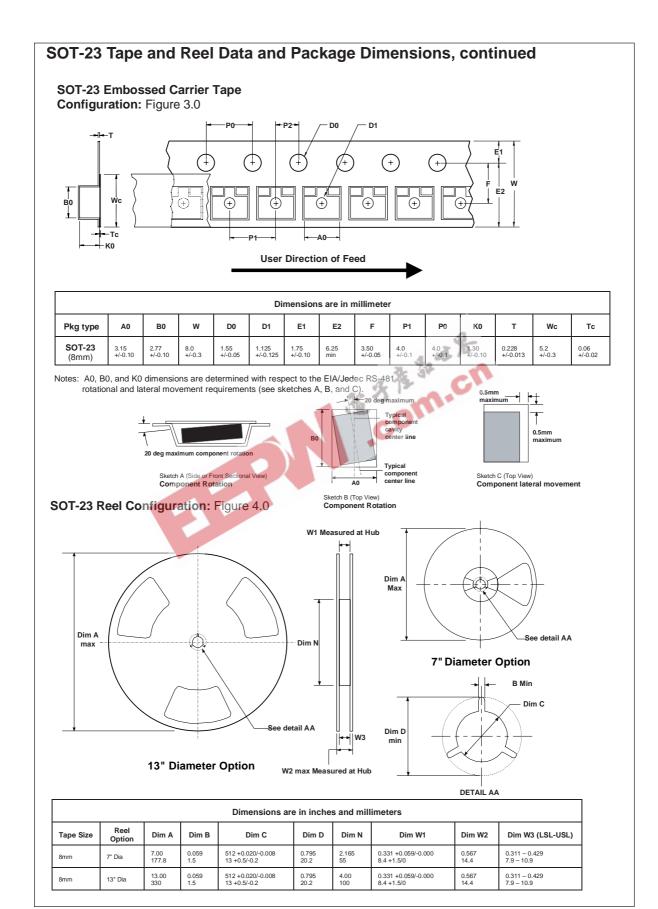


FIRST WIRE OFF IS COLLECTOR (ON PKG. 92) ADHESIVE TAPE IS ON BOTTOM SIDE FLAT OF TRANSISTOR IS ON TOP

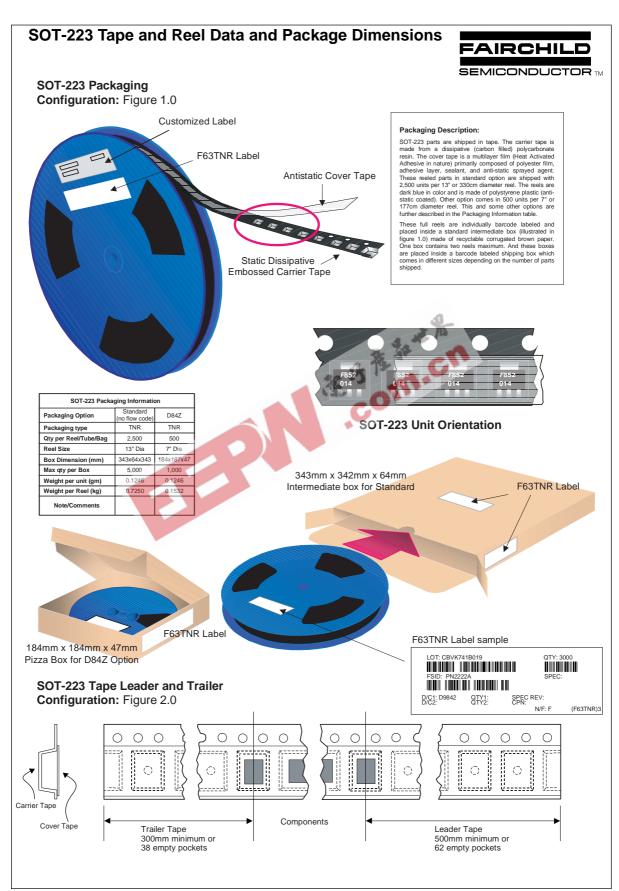


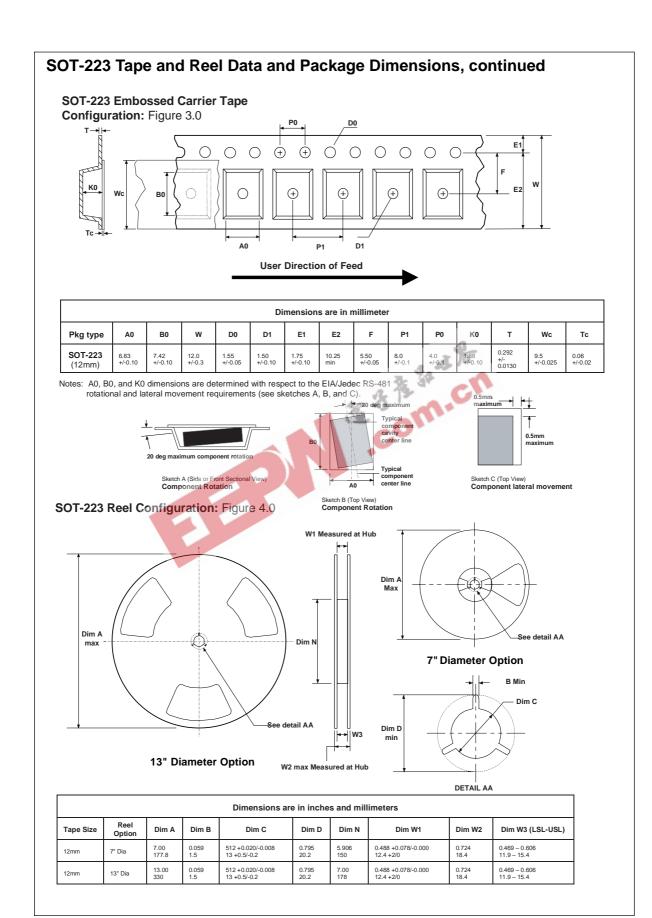






# SOT-23 Tape and Reel Data and Package Dimensions, continued SOT-23 (FS PKG Code 49) Scale 1:1 on letter size paper Dimensions shown below are in: inches [millimeters] Weight per unit (gram): 0.0082 .0750±0.0050 [1.91±0.13] -0.0510±0.0040 [1.30±0.10] 0.0910+0.0070 0.0900 [2.29] 0.0300 [0.76] -0.0160±0.0025 [0.41±0.06]TYP 0.0300 [0.76]--0.0375±0.0025 [0.95±0.06] LAND PATTERN RECOMMENDATION -0.1150±0.0050 [2.92±0.13] -0.0050±0.0020 [0.13±0.05]TYP. -0.0365 [0.93] SOT 23, 3 LEADS LOW PROFILE NOTE: UNLESS OTHERWISE SPECIFIED STANDARD LEAD FINISH 150 MICROINCHES / 3.81 MICROMETERS MINIMUM TIN / LEAD (SOLDER) ON ALLOY 42 2. REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE G, DATED JUL 1993





# SOT-223 Tape and Reel Data and Package Dimensions, continued SOT-223 (FS PKG Code 47) Scale 1:1 on letter size paper Part Weight per unit (gram): 0.1246 0.256±0.008 [6.50±0.20] 0.122 3.10 0.114 2.90 0.129MAX. [3.28]ф0.004[0.1]MQASBS \_0.1400+0.0060 3.56+0.15 0.059MAX. [1.50] $0.274^{+0.013}_{-0.010}$ EB-0.248 [6.30] -0.059MAX. 0.0900TYP. [2.29] 0.039 [0.99]TYP. -0.090 [2.29] LAND PATTERN RECOMMENDATION R0.0060±0.0020 [R0.15±0.05]TYP -GAGE PLANE 0.071 | 1.80 -0.061 | 1.55 -0.0630 [1.60] 0.0130 | 0.33 0.0090 | 0.23 0.010[0.25] 0.032 [0.82]MIN 10.0 TYP. 0.004 0.10 TYP\_ R0.006±0.002 [R0.15±0.05]TYP. 0.067 [1.70] -SEATING PLANE NOTES: UNLESS OTHERWISE SPECIFIED 1. STANDARD LEAD FINISH TO BE 150 MICROINCHES/ 3.81 MICROMETERS MINIMUM TIN/LEAD (SOLDER) ON COPPER. 2. REFERENCE JEDEC REGISTRATION TO-261, VARIATION AA, ISSUE A, DATED JAN 1990 SOT223, 4 LEADS

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